

IN THE CLAIMS:

1.-40. (Canceled)

41. (Previously Presented) A mold for molding a package for a plurality of die bonded to a substrate, the mold comprising a first mold portion that defines a package cover for encapsulating the plurality of die and a portion of a surface of the substrate to which the die are bonded, and a second mold portion that defines a plurality of ribs having a thickness at least as great as a solder bump thickness and that projects outwardly from a surface of the substrate opposite the surface of the substrate to which the plurality of die are bonded, wherein the first mold portion and the second mold portion define package covers and ribs for a plurality of die bonded to the substrate.

42.-59. (Canceled)

60. (New) The mold of claim 41, wherein the first mold portion is configured to define the package covers to encapsulate at least a portion of the surface of the substrate opposite the surface of the substrate to which the plurality of die are bonded.

61. (New) The mold of claim 60, wherein the first mold portion is configured to contact the second mold portion.

62. (New) The mold of claim 60, wherein the first mold portion is configured to define at least one cover to encapsulate at least a portion of a substrate edge.

63. (New) The mold of claim 60, wherein the second mold portion is configured to encapsulate at least a portion of a substrate edge.

64. (New) The mold of claim 41, wherein the first mold portion is configured to contact the second mold portion.